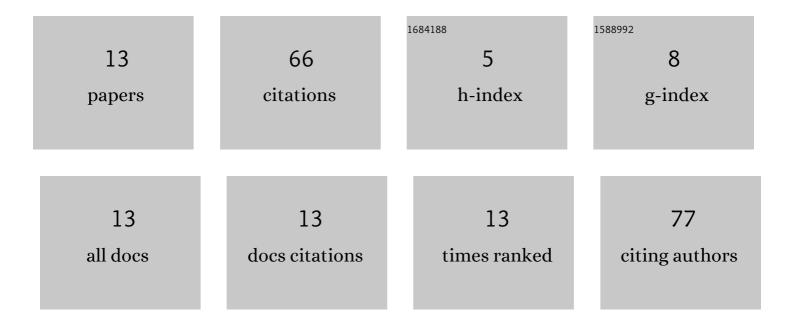
Yu-Chou Shih

List of Publications by Year in descending order

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#	Article	IF	CITATIONS
1	Screen-Printable Silver Pastes with Nanosized Glass Frits for Silicon Solar Cells. Journal of Electronic Materials, 2013, 42, 410-416.	2.2	16
2	Role of Transparent Die Attach Adhesives for Enhancing Lumen Output of Midpower LED Emitters With Standard MESA Structure. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 731-736.	2.5	12
3	Study of optimal filler size for high performance polymer-filler composite optical reflectors. Optical Materials Express, 2015, 5, 423.	3.0	9
4	Optical Interaction Between LED Backside Reflectors and Die Attach Adhesives. IEEE Photonics Technology Letters, 2016, 28, 1446-1449.	2.5	8
5	Optimal Design of a Quantum Dot Color Conversion Film in LCD Backlighting. IEEE Journal of Selected Topics in Quantum Electronics, 2017, 23, 1-4.	2.9	5
6	Effect of Thinning Encapsulant Layer on Junction and Phosphor Temperature of White Light-Emitting Diodes. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 1628-1634.	2.5	4
7	Novel Ceramic Additives for Screen-Printable Silicon Solar Cell Metallization. Journal of Electronic Materials, 2016, 45, 3999-4004.	2.2	3
8	Printable optically transparent adhesive processing for bonding of LED chips to packages. Materials Science in Semiconductor Processing, 2016, 56, 155-159.	4.0	3
9	Semiconductor Chip Electrical Interconnection and Bonding by Nano-Locking with Ultra-Fine Bond-Line Thickness. Nanomaterials, 2021, 11, 1901.	4.1	3
10	Nano-sized glass frits with surface treatment for silicon solar cells. , 2013, , .		1
11	Electrical Interconnection and Bonding by Nano-Locking. Nanomaterials, 2021, 11, 1589.	4.1	1
12	Enhanced Lumen Output of LEDs With Die Bonding by Printable Adhesive. IEEE Photonics Technology Letters, 2017, 29, 1109-1111.	2.5	1
13	Developing Cost-Effective Ultrathin Reliable High Power White LED Emitters. IEEE Transactions on Device and Materials Reliability, 2021, 21, 424-430.	2.0	0